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ACTION

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(54) Title: PROCESS FOR CREATING HOLES IN POLYMERIC SUBSTRATES

(57) Abstract: Provided is a process for creating a via through a substrate including the steps of (a) providing a substantially void-free film of a curable composition; (b) applying a resist onto the curable film; (c) imaging the resist in predetermined locations; (d) developing the resist to expose predetermined areas of the curable film; (e) removing the exposed areas of the curable film to form holes through the curable film; and (f) heating the curable film of step (e) to a temperature and for a time sufficient to cure the curable composition. Also disclosed is a process of fabricating a circuit assembly which includes building patterned circuit layers upon a substrate that has vias provided by the aforementioned process.